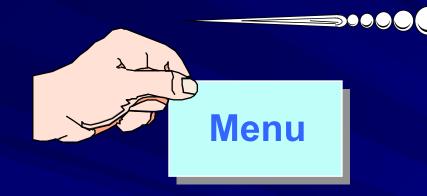
Electronics Issues & challenges for future linear colliders





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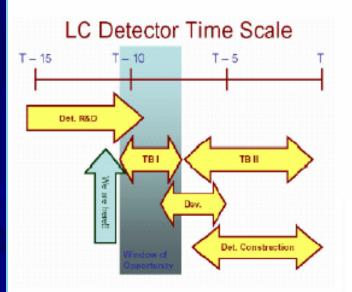


Basic parameters and constraints
 Detector concepts
 Front end electronics and read out issues
 Data collection architecture model
 Software trigger

LECC September 2004 - Boston

Goals of this presentation

Brief overview of the Read-out issues and directions for the next HEP facility : the ILC \rightarrow International Linear Collider





2005 → R&D
2007 → technology choice
2009 → begin construction
2015 → detector ready

Conditions

Recent International decision: « cold » machine ' à la Tesla'

Machine parameters

2 x 16 km superconducting
 Linear independant accelerators
 2 interaction points
 2 detectors
 Energy

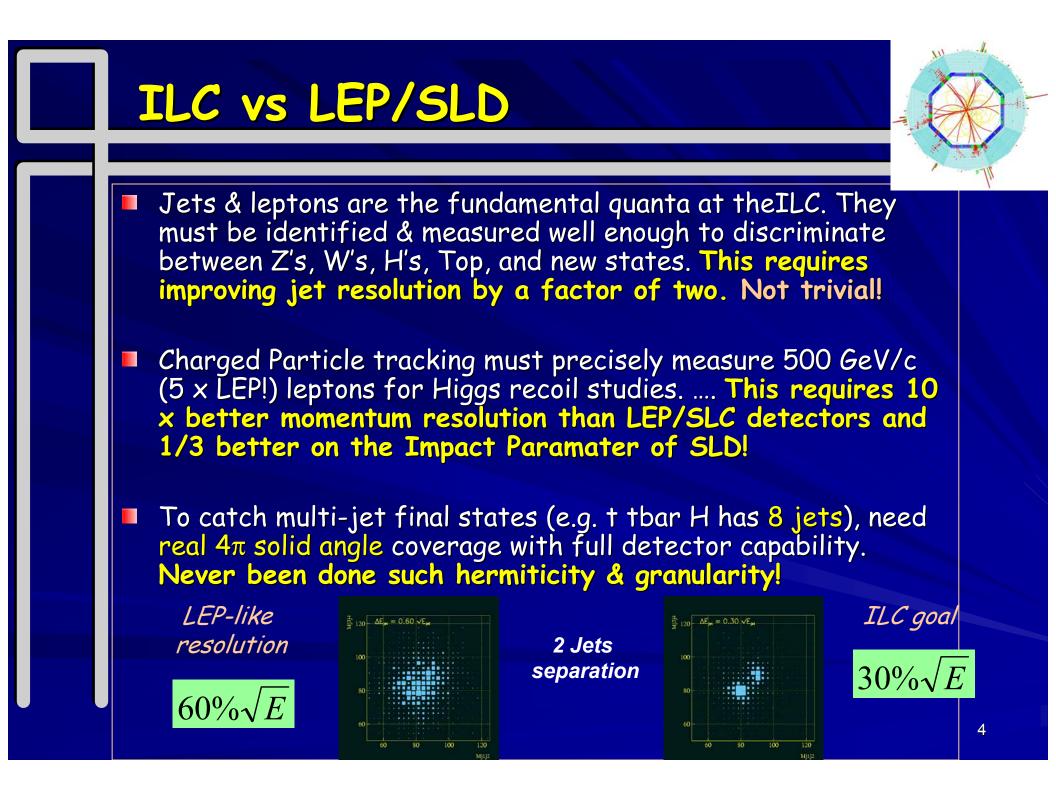
 nominale : 500 Gev

- maximum : 1 Tev
- IP beam size ~ 1 μm



repetitian rate	5
bunches per train	2820
bunch separation	337 ns
train length	950 ns
train separation	199 ms

-> long time between trains (short between pulses)



ILC vs LHC

Less demanding

LC Detector doesn't have to cope with multiple minimum bias events per crossing, high rate triggering for needles in haystacks, radiation hardness...

 \rightarrow hence many more technologies available, better performance is possible.

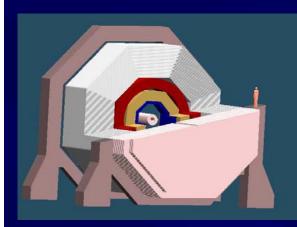
BUT → LC Detector does have to cover full solid angle, record all the available CM energy, measure jets and charged tracks with unparalleled precision, measure beam energy and energy spread, differential luminosity, and polarization, and tag all vertices,...

 \rightarrow hence better performance needed, more technology development needed.

Complementarity with LHC \rightarrow discovery vs precison

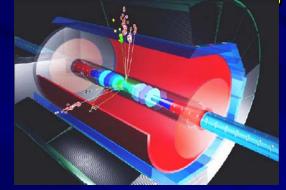
The 'Particle flow' paradigm in calorimeters !

→ LC should strive to do physics with *all* final states. Charged particles in jets more precisely measured in tracker Good separation of charged and neutral

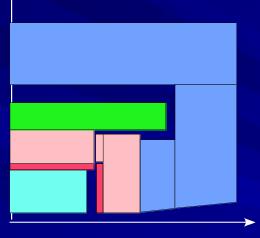


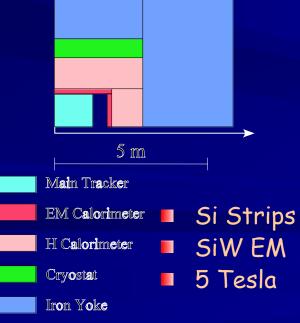
SiD

Detector concepts

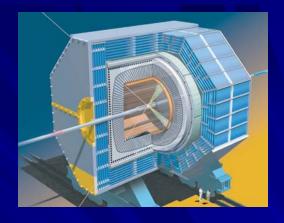


Tesla (TDR)





- Large gaseous central tracking device (TPC)
- High granularity calorimeters
- High precision microvertex
- All inside 4T magnetic field

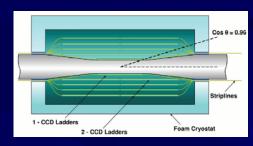


Huge

■ Large Gazeous Tracker → JET, TPC

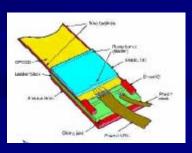
- W/Scint EM calor.
- 3 Teslas solenoid

	Evoluti	ion of	basic	param	ete	ers							
Exp. Year	Collision rate	Channel count	L1A rate	Event building		ocessing. Power So		ology					
UA's <u>1980</u>	3 µsec	-	-	-	5-1(5-10 MIPS		-200					
LEP 1989	10-20 µsec	250 - 500K	-	10 Mbit/sec	100 MIPS		100 MIPS 3		MIPS 300		300-500		
BaBar <u>1999</u>	4 ns	150K	2 KHz	400 Mbit/s	1000 MIPS		400						
Tevatron	396 ns	~ 800 K	10 - 50 KHz	4-10 Gbit/sec	5.10	5.10 ⁴ MIPS		00					
LHC 2007	25 ns	200 M*	100 KHz	20-500 Gbit/s	>10	>10 ⁶ MIPS		00	-				
ILC 2015 ?	330 ns	900 M*	3 KHz	10 Gbit/s	~10	⁵ MIPS	> 2000 ?						
* including pixels			ls Si	Sub-Detector		LHC		ILC					
				Pixel			150 M		800 M				
Microstrips				~ 1(D M	3	0 M					
	Fine grain trackers				ers ~ 40)0 K <mark>1</mark> ,		5 M				
			Calorimeters			200 K		3	0 M				
				Muon	~1 M								



CCD (C. Dammerell & al.)

- SLD/VXD3 experience, but needs faster readout and rad hard design.
- Column-parallel CCD with low noise, very low driving Voltage and 50 MHz ASIC.
- Read Out 20 time per Bunch Train (50 µs)
- RO Full detector $\rightarrow 2 \times 1$ GByte fiber



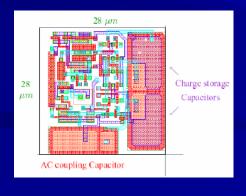
Vertex technologies

CMOS

(Monolhitic Active Pixel Sensor)

(IRES Strasbourg)

- Concept from visible light imagers
- fast readout and on-chip integration of functionalities 20x20 µm cell CMOS sensor
- neutron fluxes 100 times larger than expected at LC,
- gives 2 µm resolution in beam tests
- thinned down to 120 μm.
- Adopted for STAR VTX upgrade at RHIC



Mimosa 6

DEPFETetc (Bonn,MPI)

- FET-Transistor integrated in every pixel (first amplification)
- No charge transfer
- Very limited power consumption (~ 5W for the full VD)
- Low noise allows 50 μm thinned down sensors

Common Challenges

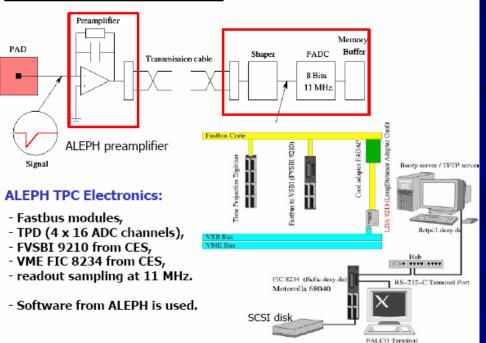
- Everything ON detector
- Collumn RO & sparcification
- Power cycling
- Read-out during Bunch Train → Influence of RF pick-up?

8

TPC Read Out

TPC : a typical readout à la ALEPH

From present (Aleph)

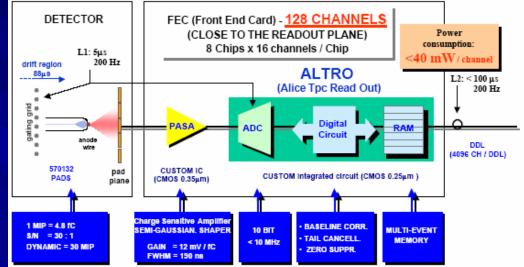


Main Features

- VFE: GEM/Micromegas, Digital (Medipix)
- No active gating
- Continuous Read Out during the full bunch train (1ms)
- Minimize RO material in the end cap !

To future (investigate Alice RO model?)

The ALICE TPC Front End Electronics Source: L.Musa (for the Alice Collaboration)



A single readout channel is comprised of:

- a charge sensitive amplifier / shaper
- a 10-bit low power ADC
- a digital circuit for the tail cancellation, zero suppression, etc...
- a multi-event buffer (up to 8 event data streams)

Calorimeters Read Out

 Today
 CALICE UK group, P. Dauncey

 PCI-VME interface
 PCI-VME interface

 x30 layers
 Cables

 Gables
 Cables

 Image: Cables
 Image: Cables

 Image: Cables

RO every Xing (300ns)
 Uniform : EM,Hcal,Tail
 ~ 30 Million channels (SiW)
 Local Sparcification/buffer
 ASIC with 1024 channels
 Power cycling

APD fibre masks or flat-band connector to Si-PM cassette RO printed circuit



Technology forecast (2005-2015)

FPGA for signal processing and buffering

- Integrates receiver links, PPC, DSPs and memory
- Processors and memories

Continuous increasing of the computing power
 More's law still true until 2010! Expect x 64 by 2015!

Memory size quasi illimited !

Today : 256 MB
2010 : > 1 GB ... then ?

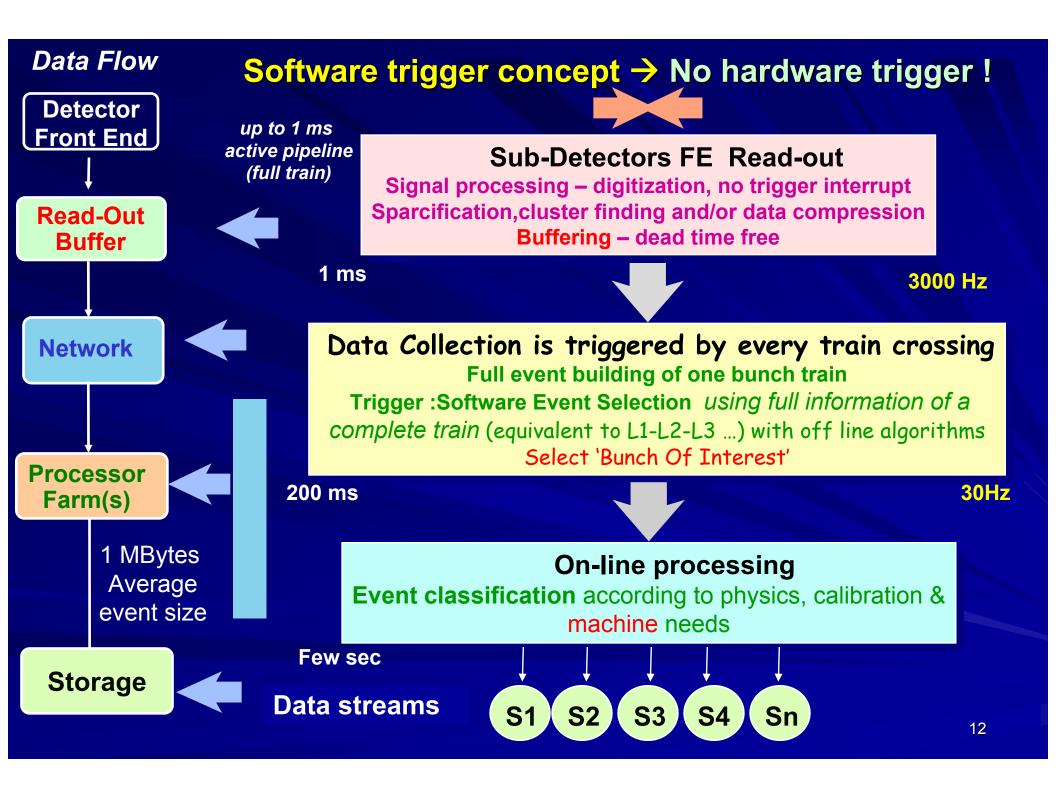
Links & Networks:

- Commercial telecom/computer standards
- 10 30 100 GBEthernet !

Systematic use of COTS products

→ make decision at TO -3 years





Advantages \rightarrow all

> Flexible

- fully programmable
- unforeseen backgrounds and physics rates easily accomodated
- Machine people can adjust the beam using background events

Easy maintenance and cost effective

- Commodity products : Off the shelf technology (memory, switches, procsessors)
- Commonly OS and high level languages
- on-line computing ressources usable for « off-line »

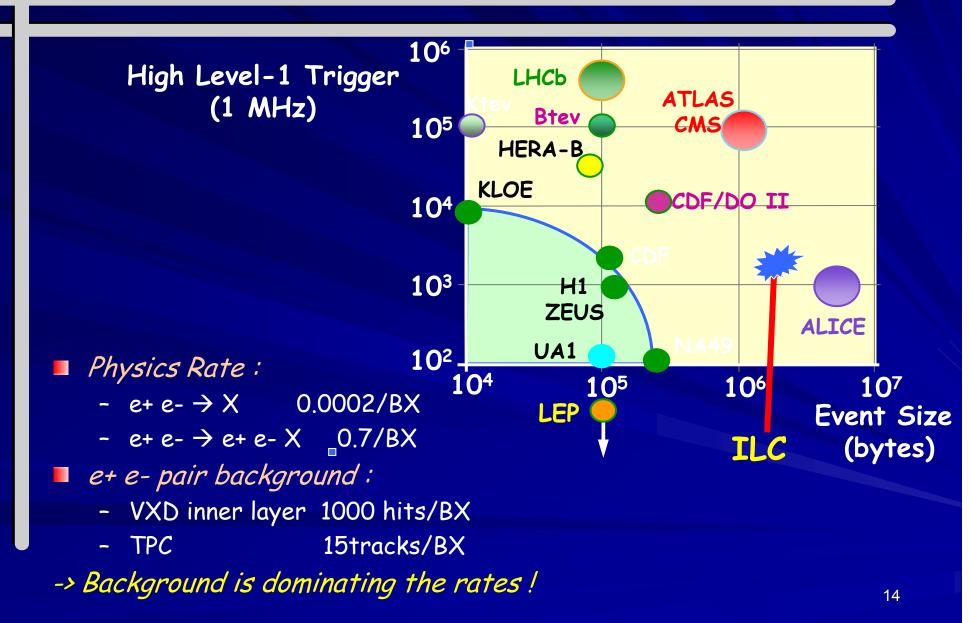
> Scalable :

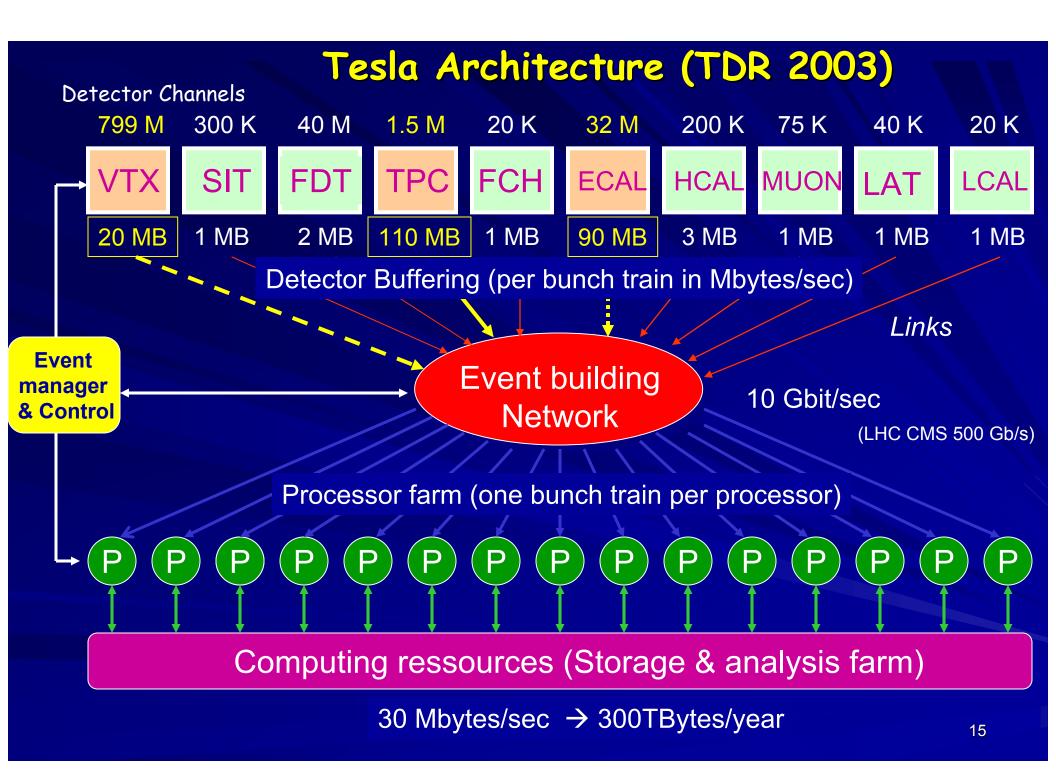
- modular system

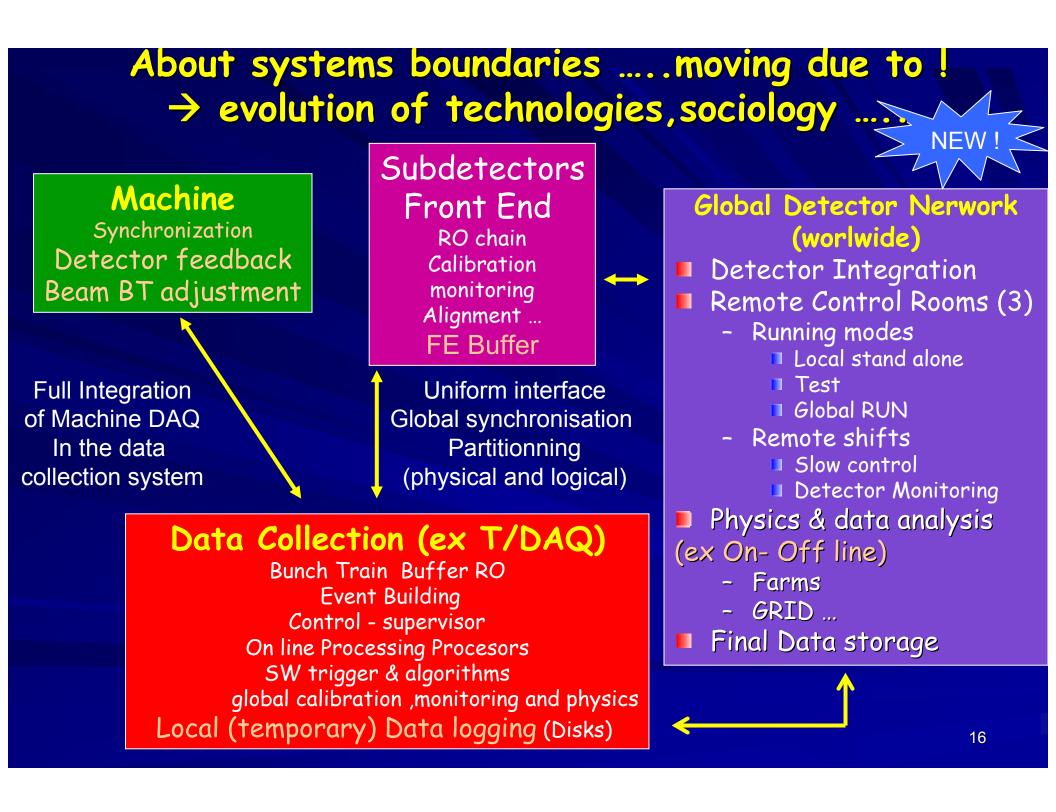
Looks like the 'ultimate trigger '

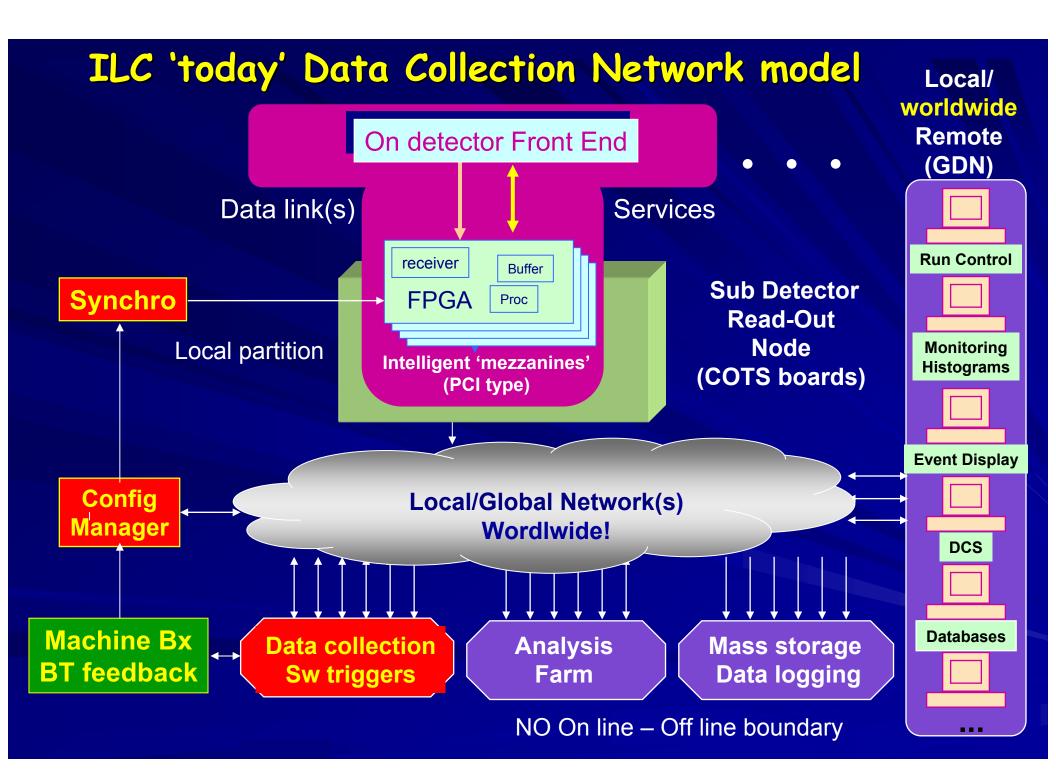
satisfy everybody : no loss and fully programmable

Estimates Rates and data volume











Summary

The ILC environment poses new challenges & opportunities which will need new technical advances in VFE and RO electronics \rightarrow NOT LEP/SLD, NOT LHC! Basic scheme: The FEE integrates everything →From signal processing & digitizer to the RO BUFFER Very large number of channels to manage (Trakers & EM) ->should exploit power pulsing to cut power usage during interburst ■ New System aspects (boundaries $.. \rightarrow GDN$!) Interface between detector and machine is fundamental \rightarrow optimize the luminosity \rightarrow consequence on the DAQ Burst mode allows a fully software trigger →Looks like the Ultimate Trigger: Take EVERYTHING & sort later ! \rightarrow GREAT! A sociological simplification!